

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

ON Semiconductor®

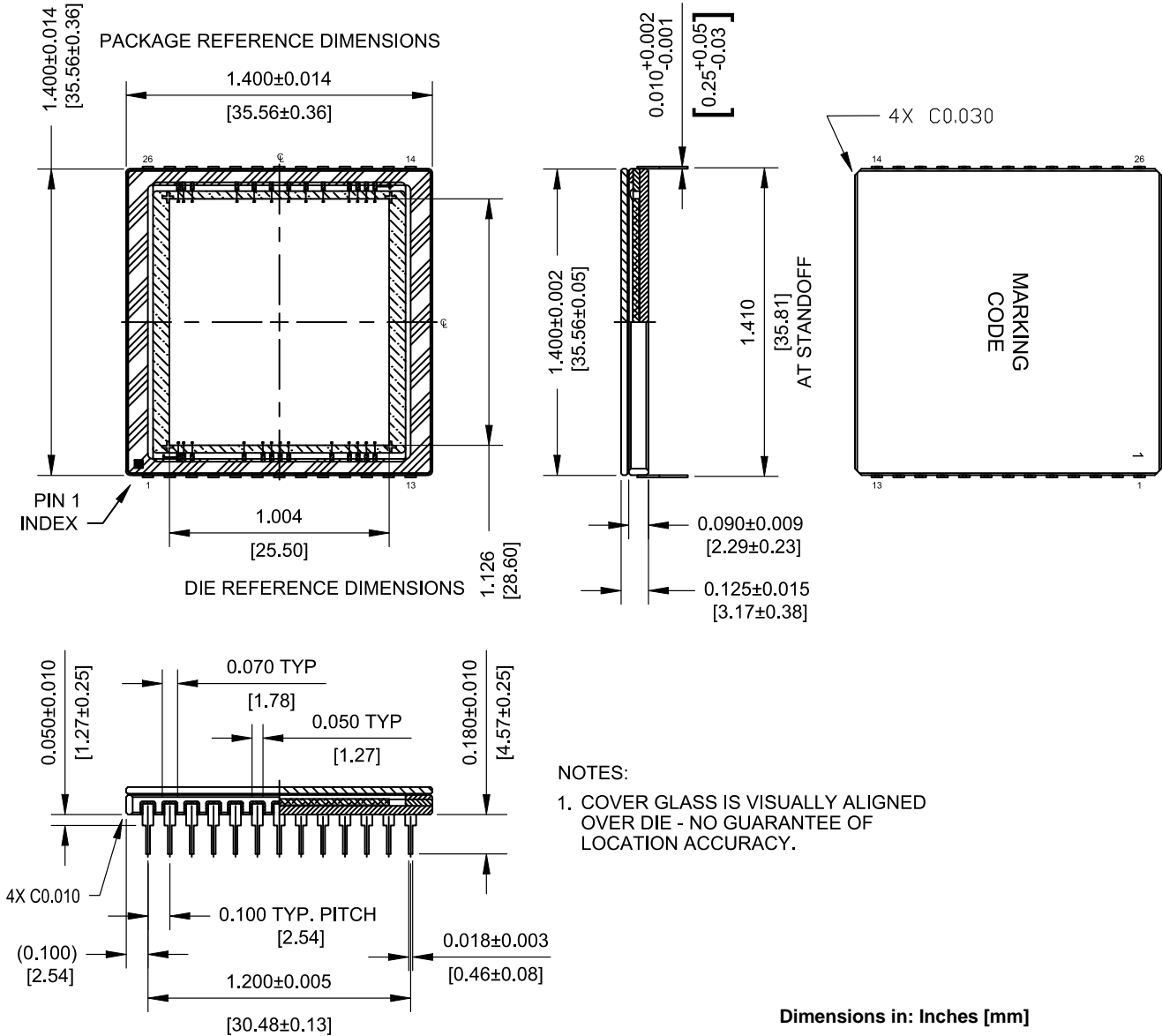


CERAMIC DIP 26, 35.56x35.56

CASE 125AZ

ISSUE O

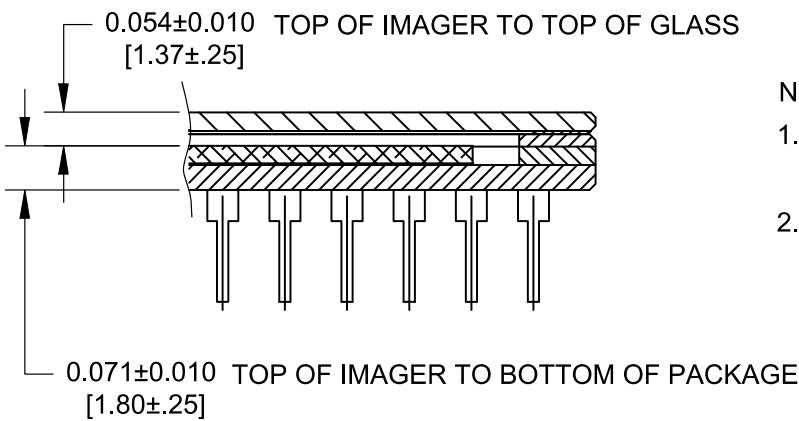
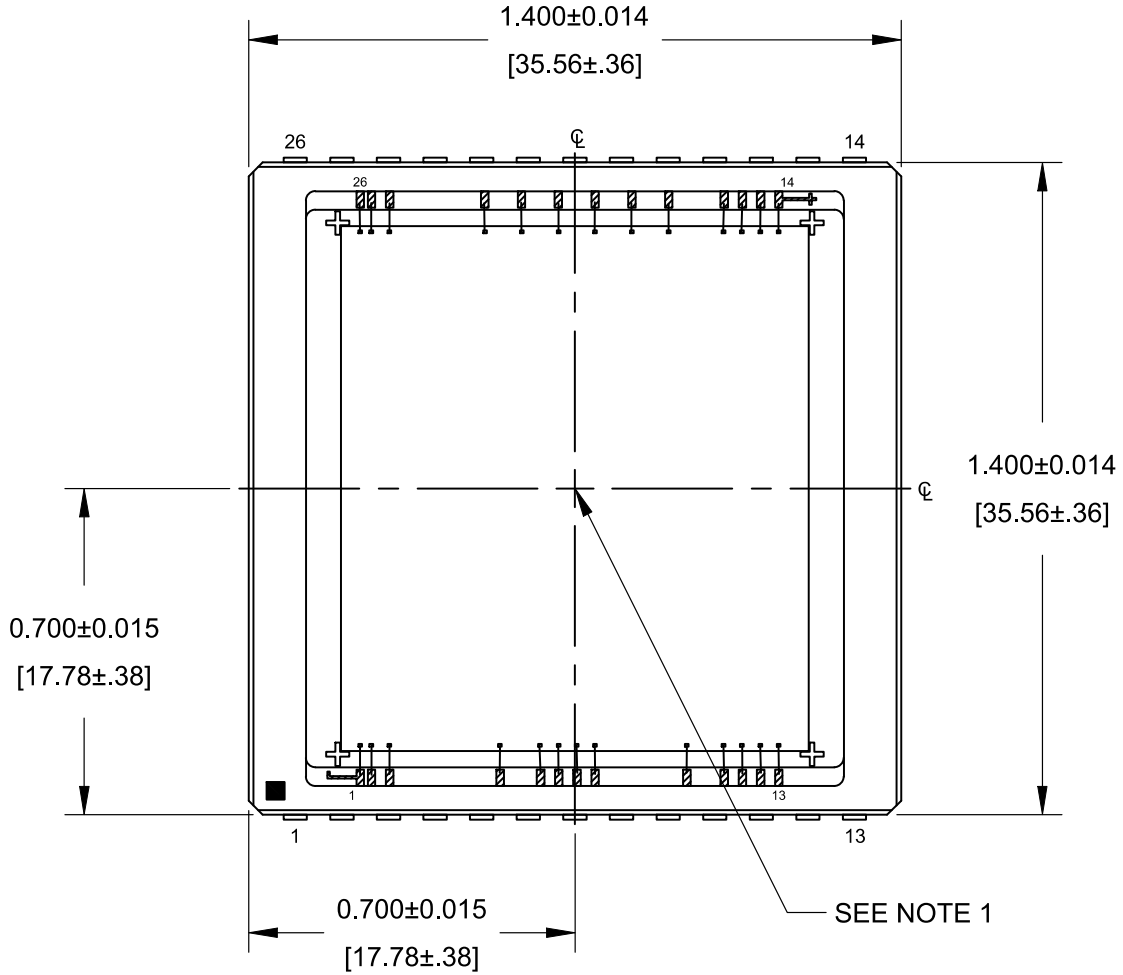
DATE 30 JUL 2014



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CERAMIC DIP 26, 35.56x35.56
CASE 125AZ
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NOTES:

1. CENTER OF IMAGE AREA IS OFFSET FROM CENTER OF PACKAGE BY (0.00,0.00)mm NOMINAL.
2. DIE IS VISUALLY ALIGNED WITHIN $\pm 2^\circ$ OF ANY PACKAGE CAVITY EDGE.

Dimensions in: Inches [mm]

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